

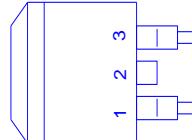
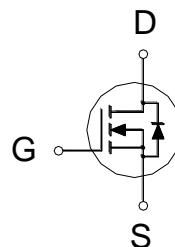
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****P2610BS**

TO-263

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	26.8mΩ	36A



1: GATE
2: DRAIN
3: SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ C$	I_D	36	A
	$T_C = 100^\circ C$		23	
Pulsed Drain Current ¹		I_{DM}	70	A
Avalanche Current		I_{AS}	11	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	6	mJ
Power Dissipation	$T_C = 25^\circ C$	P_D	83	W
	$T_C = 100^\circ C$		33	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		62.5	°C / W
Junction-to-Case	$R_{\theta JC}$		1.5	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ C$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.8	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80V, V_{GS} = 0V$			1	μA
		$V_{DS} = 80V, V_{GS} = 0V, T_J = 125^\circ C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$		23	35	$m\Omega$
		$V_{GS} = 10V, I_D = 10A$		22	26.8	

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Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 10A$	50		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	1929		pF
Output Capacitance	C_{oss}		139		
Reverse Transfer Capacitance	C_{rss}		87		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	0.8		Ω
Total Gate Charge ²	$Q_{g(VGS=10V)}$		41		nC
	$Q_{g(VGS=4.5V)}$		21.5		
Gate-Source Charge ²	Q_{gs}		6		
Gate-Drain Charge ²	Q_{gd}		12		
Turn-On Delay Time ²	$t_{d(on)}$		15		nS
Rise Time ²	t_r	$V_{DS} = 50V, I_D \geq 10A,$	43		
Turn-Off Delay Time ²	$t_{d(off)}$	$V_{GS} = 10V, R_{GEN} = 6\Omega$	45		
Fall Time ²	t_f		37		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)					
Continuous Current	I_S			36	A
Forward Voltage ¹	V_{SD}	$I_F = 10A, V_{GS} = 0V$		1.2	V
Diode Reverse Recovery Time	t_{rr}		32		nS
Diode Reverse Recovery Charge	Q_{rr}	$I_F = 10A, dI/dt = 100A/\mu s$	36		nC

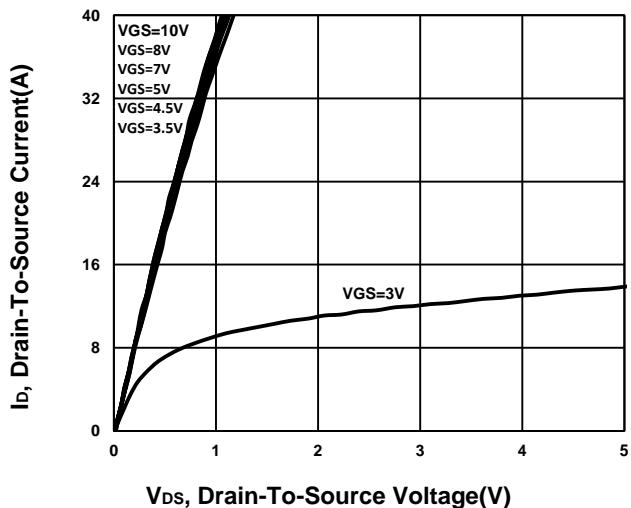
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

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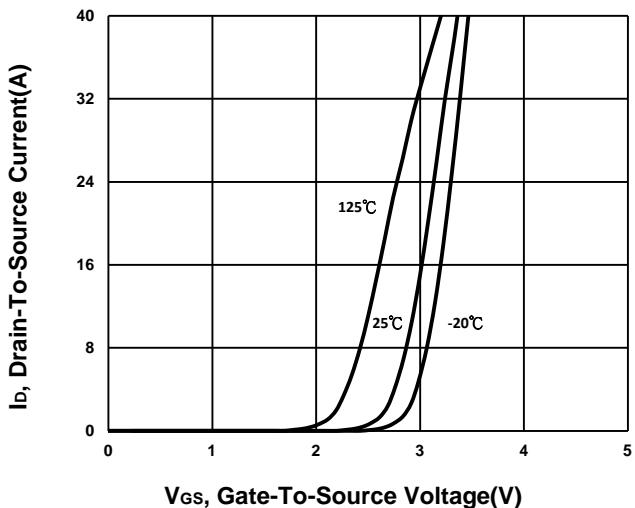
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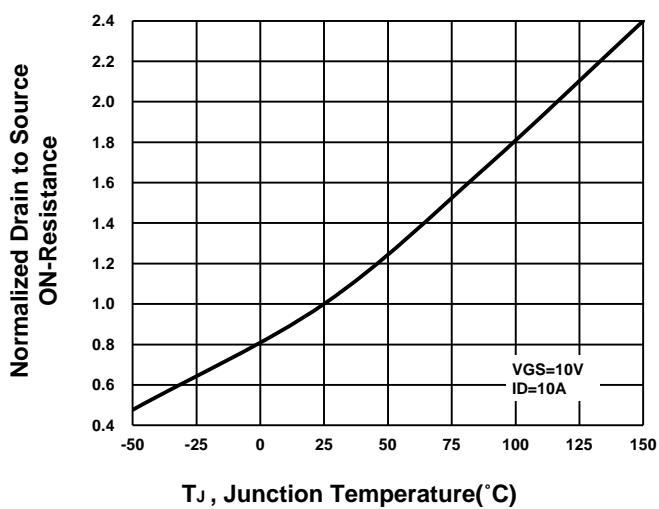
Output Characteristics



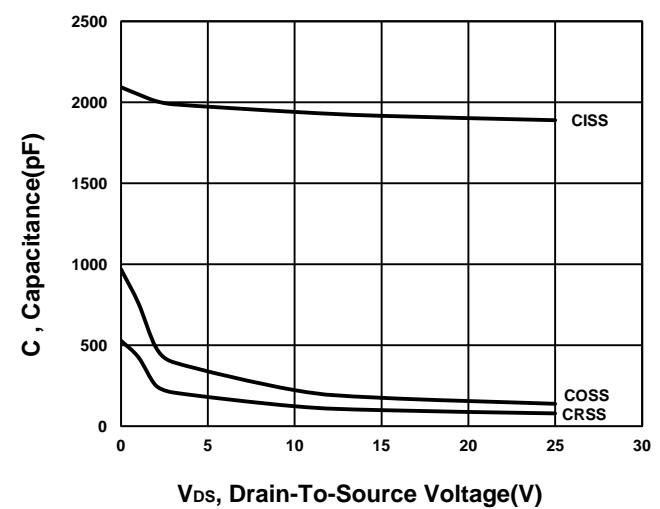
Transfer Characteristics



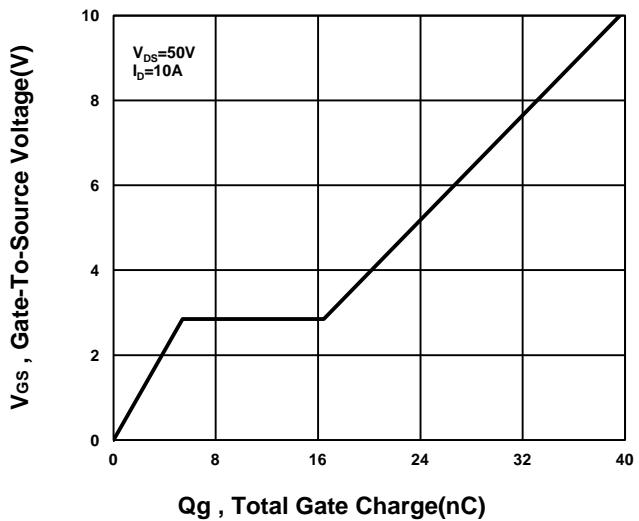
On-Resistance VS Temperature



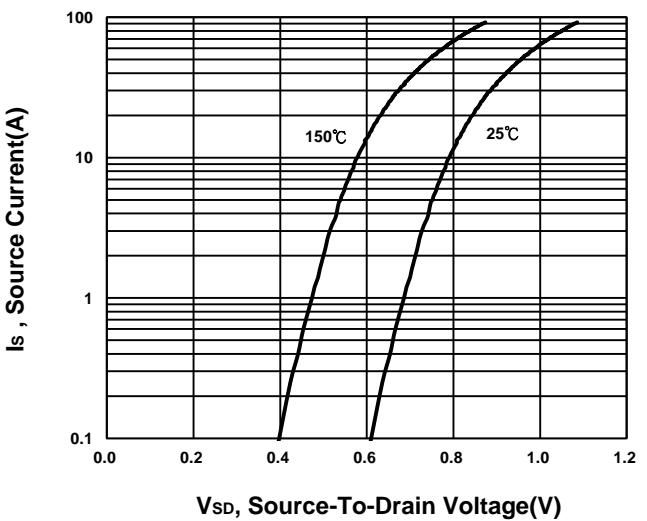
Capacitance Characteristic



Gate charge Characteristics



Source-Drain Diode Forward Voltage

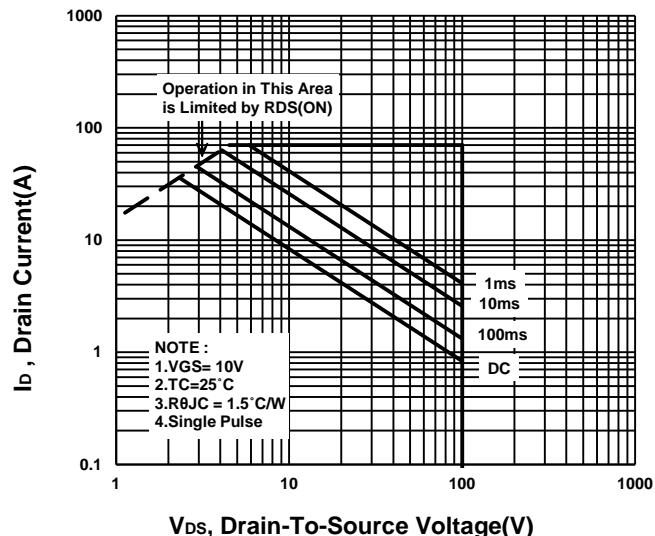


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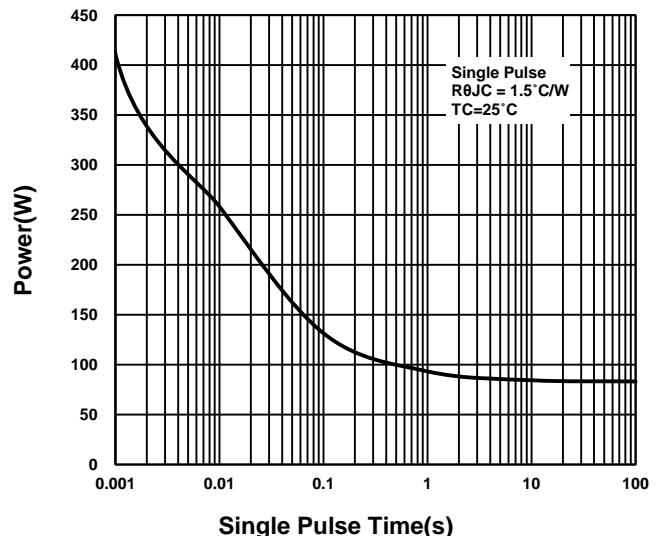
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Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

